

**Reaction Bonded Silicon Carbide ceramic**  
 Technical Parameter of SISIC products

Item	Unit	Data
temperature of application	°C	1380
density	g/cm <sup>3</sup>	>3.02
open porosity	%	<0.1
bending strength	Mpa	250(20°C)
	Mpa	280(1200°C)
modulus of elasticity	Gpa	330(20°C)
	Gpa	300(1200°C)
thermal conductivity	W/m.k	45(1200°C)
coefficient of thermal expansion	k <sup>-1</sup> × 10 <sup>-6</sup>	4.5
Vickers Hardness HV <sub>10</sub>	Gpa	20
acid-proof alkaline		Excellent

The values for above are the typical result from the test,not the promised exactly data applied to all orders

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